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2	19740	(copper and stress) and (interconnect$ or wiring)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/11 09:58
3	10853	((copper and stress) and (interconnect$ or wiring)) and semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/11 09:58
4	9730	(((copper and stress) and (interconnect$ or wiring)) and semiconductor) and (hole or via or opening or slit or slot)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/11 10:00
5	7056	((((copper and stress) and (interconnect$ or wiring)) and semiconductor) and (hole or via or opening or slit or slot)) and etch$	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/11 10:00
6	5413	(((((copper and stress) and (interconnect$ or wiring)) and semiconductor) and (hole or via or opening or slit or slot)) and etch$) and via	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/11 10:02
7	1202	((((((copper and stress) and (interconnect$ or wiring)) and semiconductor) and (hole or via or opening or slit or slot)) and etch$) and via) and (relief or migrat$)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/11 10:54
8	1845	copper and (stress adj relief)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/11 10:55
9	633	(copper and (stress adj relief)) and etch$	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/11 10:56

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